

ABSOLUTE MAXIMUM RATINGS (1)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
INPUT				
Reverse voltage		V_R	6	V
DC forward current		I_F	50	mA
Surge forward current	$t_p \leq 10 \mu s$	I_{FSM}	2.5	A
Total power dissipation		P_{diss}	70	mW
OUTPUT				
Collector emitter voltage		V_{CE}	55	V
Collector base voltage		V_{CBO}	55	V
Emitter base voltage		V_{EBO}	7	V
Collector current		I_C	50	mA
Surge collector current	$t_p \leq 1.0 ms$		100	mA
Total power dissipation		P_{diss}	150	mW
COUPLER				
Isolation test voltage between emitter and detector	$t = 1.0 s$	V_{ISO}	5300	V _{RMS}
Creepage distance			≥ 7	mm
Clearance distance			≥ 7	mm
Comparative tracking index per DIN IEC 112/VDE0303, part 1			175	
Isolation resistance	$V_{IO} = 500 V, T_{amb} = 25 ^\circ C$	R_{IO}	$\geq 10^{12}$	Ω
	$V_{IO} = 500 V, T_{amb} = 100 ^\circ C$	R_{IO}	$\geq 10^{11}$	Ω
Storage temperature range		T_{stg}	- 55 to + 150	$^\circ C$
Operating temperature range		T_{amb}	- 55 to + 100	$^\circ C$
Soldering temperature (2)	max. 10 s, dip soldering: distance to seating plane $\geq 1.5 mm$	T_{sld}	260	$^\circ C$

Notes(1) $T_{amb} = 25 ^\circ C$, unless otherwise specified.

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

(2) Refer to reflow profile for soldering conditions for surface mounted devices (SMD). Refer to wave profile for soldering conditions for through hole devices (DIP).

ELECTRICAL CHARACTERISTICS

PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT							
Forward voltage	$I_F = 5 mA$		V_F		1.1	1.5	V
Reverse voltage	$I_R = 10 \mu A$		V_R	6			V
Reverse current	$V_R = 6 V$		I_R		0.01	10	μA
Capacitance	$V_R = 0 V, f = 1 MHz$		C_O		25		pF
Thermal resistance			R_{thja}		1070		K/W
OUTPUT							
Collector emitter voltage	$I_{CE} = 10 \mu A$		V_{CEO}	55			V
Emitter base voltage	$I_{EB} = 10 \mu A$		V_{EBO}	7			V
Collector emitter capacitance	$V_{CE} = 5 V, f = 1 MHz$		C_{CE}		10		pF
Collector base capacitance	$V_{CE} = 5 V, f = 1 MHz$		C_{CB}		16		pF
Emitter base capacitance	$V_{CE} = 5 V, f = 1 MHz$		C_{EB}		10		pF
Thermal resistance			R_{thja}		500		K/W
Collector emitter leakage current	$V_{CE} = 10 V$		I_{CEO}		10	200	nA



Optocoupler, Phototransistor Output, Vishay Semiconductors
Low Input Current, with Base
Connection, 5300 V_{RMS}

ELECTRICAL CHARACTERISTICS

PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
COUPLER							
Coupling capacitance			C _C		0.6		pF
Saturation voltage, collector emitter	I _C = 0.32 mA, I _F = 1 mA	SFH608-2	V _{CEsat}		0.25	0.4	V
	I _C = 0.5 mA, I _F = 1 mA	SFH608-3	V _{CEsat}		0.25	0.4	V
	I _C = 0.8 mA, I _F = 1 mA	SFH608-4	V _{CEsat}		0.25	0.4	V
	I _C = 1.25 mA, I _F = 1 mA	SFH608-5	V _{CEsat}		0.25	0.4	V

Note

T_{amb} = 25 °C, unless otherwise specified.

Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

CURRENT TRANSFER RATIO

PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
Coupling transfer ratio	I _F = 1 mA, V _{CC} = 0.5 V	SFH608-2	CTR	63		125	%
	I _F = 0.5 mA, V _{CC} = 1.5 V	SFH608-2	CTR	32	75		%
	I _F = 1 mA, V _{CC} = 0.5 V	SFH608-3	CTR	100		200	%
	I _F = 0.5 mA, V _{CC} = 1.5 V	SFH608-3	CTR	50	120		%
	I _F = 1 mA, V _{CC} = 0.5 V	SFH608-4	CTR	160		320	%
	I _F = 0.5 mA, V _{CC} = 1.5 V	SFH608-4	CTR	80	200		%
	I _F = 1 mA, V _{CC} = 0.5 V	SFH608-5	CTR	250		500	%
	I _F = 0.5 mA, V _{CC} = 1.5 V	SFH608-5	CTR	125	300		%

SWITCHING CHARACTERISTICS

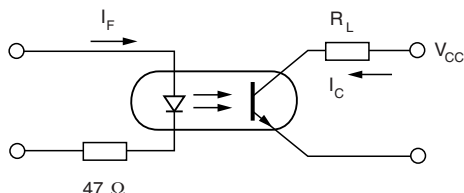
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Turn-on time	I _C = 2 mA (to adjust by I _F), R _L = 100 Ω, V _{CC} = 5 V	t _{on}		8		μs
Rise time	I _C = 2 mA (to adjust by I _F), R _L = 100 Ω, V _{CC} = 5 V	t _r		5		μs
Turn-off time	I _C = 2 mA (to adjust by I _F), R _L = 100 Ω, V _{CC} = 5 V	t _{off}		7.5		μs
Fall time	I _C = 2 mA (to adjust by I _F), R _L = 100 Ω, V _{CC} = 5 V	t _f		7		μs

SAFETY AND INSULATION RATINGS

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Climatic classification (according to IEC 68 part 1)				55/100/21		
Comparative tracking index		CTI	175		399	
V _{IOTM}			8000			V
V _{IORM}			890			V
P _{SO}					700	mW
I _{SI}					400	mA
T _{SI}					175	°C
Creepage distance	standard DIP-6		7			mm
Clearance distance	standard DIP-6		7			mm
Creepage distance	400 mil DIP-6		8			mm
Clearance distance	400 mil DIP-6		8			mm
Insulation thickness, reinforced rated	per IEC 60950 2.10.5.1		0.4			mm

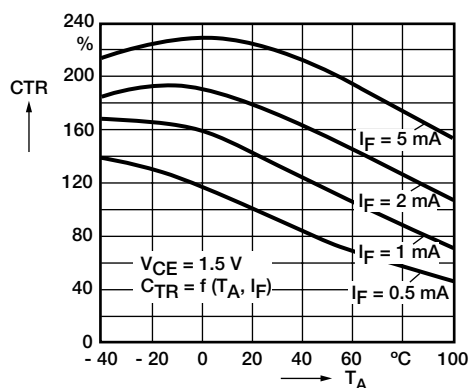
Note

As per IEC 60747-5-2, § 7.4.3.8.1, this optocoupler is suitable for "safe electrical insulation" only within the safety ratings. Compliance with the safety ratings shall be ensured by means of protective circuits.

TYPICAL CHARACTERISTICST_{amb} = 25 °C, unless otherwise specified

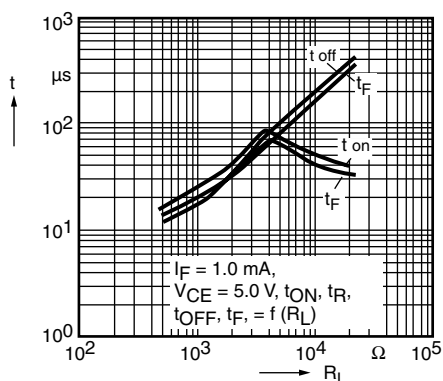
isfh608_01

Fig. 1 - Switching Schematic



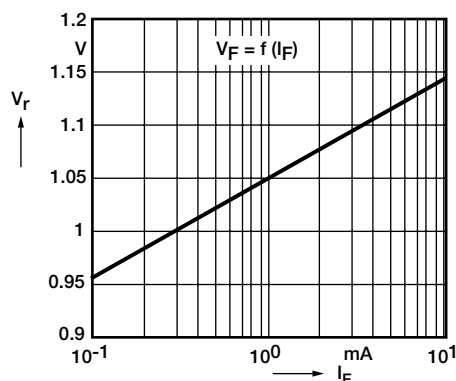
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Fig. 4 - Current Transfer Ratio (typ.)



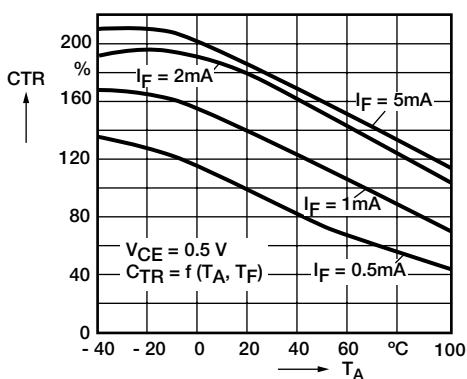
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Fig. 2 - Switching Times



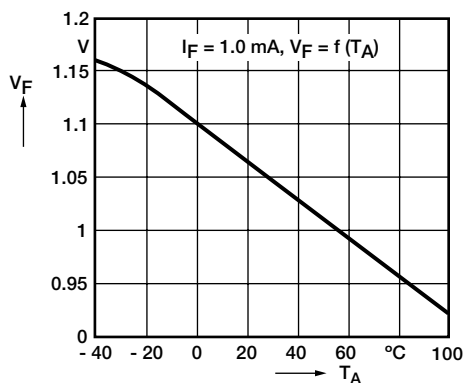
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Fig. 5 - Diode Forward Voltage (typ.)



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Fig. 3 - Current Transfer Ratio (typ.)

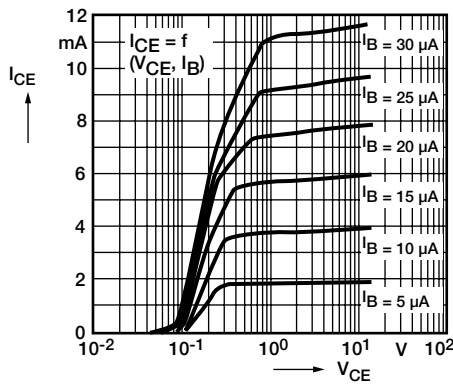


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Fig. 6 - Diode Forward Voltage (typ.)

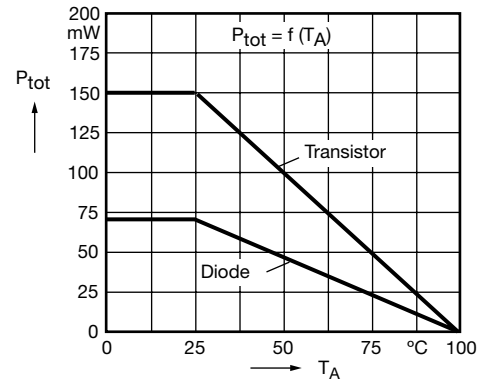
Optocoupler, Phototransistor Output, Vishay Semiconductors

Low Input Current, with Base Connection, 5300 V_{RMS}



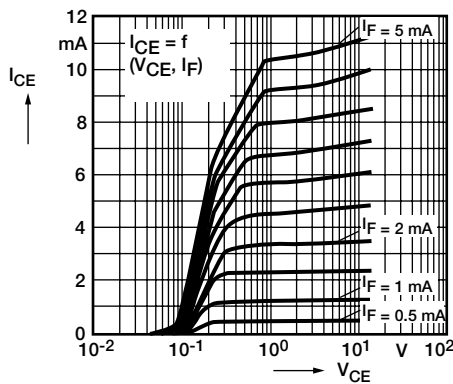
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Fig. 7 - Output Characteristics



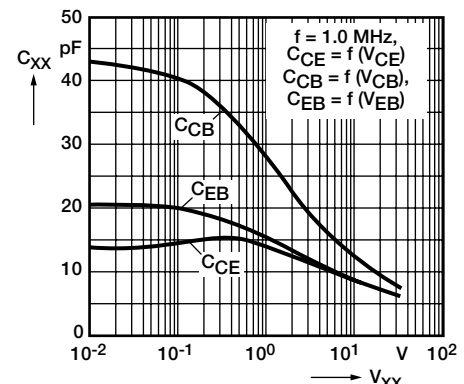
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Fig. 10 - Permissible Power Dissipation for Transistor and Diode



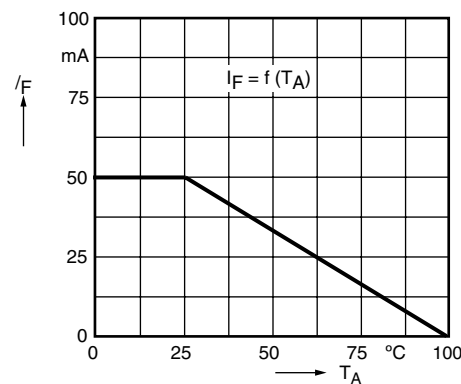
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Fig. 8 - Output Characteristics



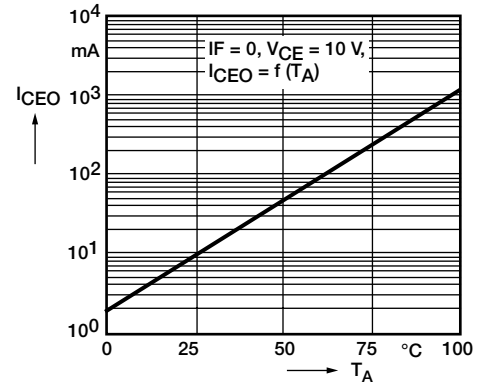
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Fig. 11 - Transistor Capacitance



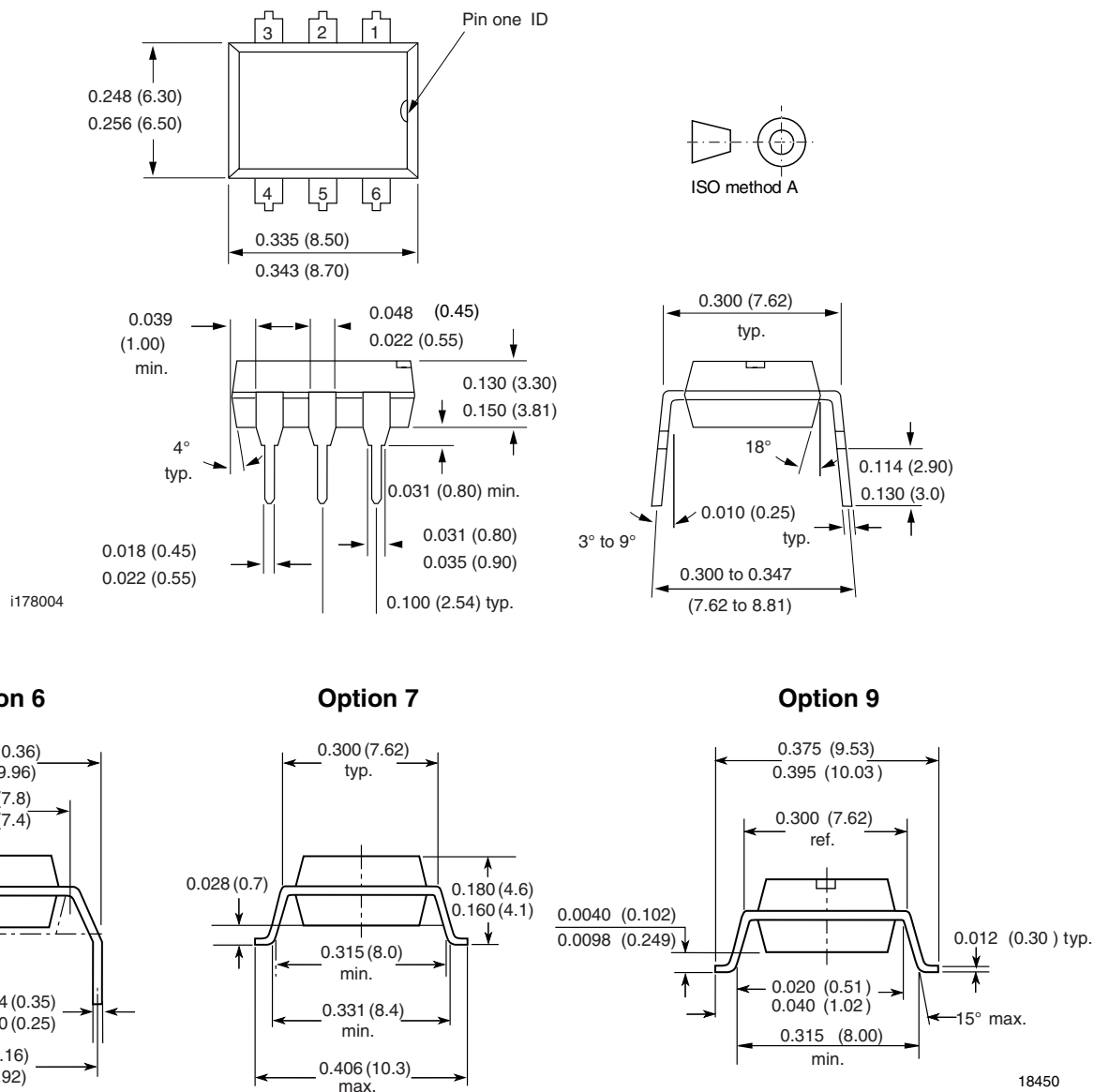
isfh608_09

Fig. 9 - Permissible Forward Current Diode



isfh608_12

Fig. 12 - Collector Emitter Leakage Current vs. Temperature

PACKAGE DIMENSIONS in inches (millimeters)



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Low Input Current, with Base
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OZONE DEPLETING SUBSTANCES POLICY STATEMENT

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively.
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA.
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design
and may do so without further notice.

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